

Abstract

This is an interconnection between electronic devices and other assemblies (e.g. printed circuits). The electronic devices are mounted on high temperature insulating bases, such as ceramic substrates. The insulating base has a conductive pattern to connect the electronic device to another assembly. The conductive pattern terminates in metal bumps capable of being connected to another assembly (e.g. a printed circuit) by a conductive adhesive or metallurgically by soldering, thermocompression, thermosonic or ultrasonic bonding. The bumps are formed by applying a metal with a melting point over 350°C to contact pads of the conductive pattern of the insulating base, and raising the temperature of the base above the melting point of the metal causing the molten metal to draw back on to the contact pads forming a convex bump.

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